



Material Content Data Sheet

Sales Product Name	TLE6251G			Issued		28. August 2013		
MA#	MA001050444							
Package	P-DSO-14-13			Weight*		136.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.435	3.98	3.98	39791	39791
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		110	
	non noble metal	zinc	7440-66-6	0.060	0.04		441	
	non noble metal	iron	7439-89-6	1.203	0.88		8811	
	non noble metal	copper	7440-50-8	48.860	35.77	36.70	357743	367105
wire	noble metal	gold	7440-57-5	0.203	0.15	0.15	1484	1484
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.095	0.80		8018	
	plastics	brominated resin	-	1.173	0.86		8590	
	organic material	carbon black	1333-86-4	1.251	0.92		9163	
	plastics	epoxy resin	-	16.035	11.74		117402	
	inorganic material	silicondioxide	60676-86-0	58.663	42.95	57.27	429518	572691
leadfinish	non noble metal	lead	7439-92-1	0.130	0.10		951	
	non noble metal	tin	7440-31-5	0.467	0.34	0.44	3421	4372
plating	noble metal	silver	7440-22-4	0.214	0.16	0.16	1570	1570
glue	plastics	epoxy resin	-	0.532	0.39		3896	
	noble metal	silver	7440-22-4	1.242	0.91	1.30	9091	12987
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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